a doped silicon temperature sensitive resistor element disposed on the peripheral portion of the top surface of said diaphragm opposite to said clamp ring.

7. A thermally compensated silicon pressure sensor as claimed in claim 6, further comprising:

a first set of electrical terminals disposed on said diaphragm portion in ohmic contact with said at least one resistor element; and

a second set of electrical terminals disposed in ohmic contact with said temperature sensitive resistor element.

8. A thermally compensated silicon pressure sensor as claimed in claim 7, wherein:

said at least one resistor element comprises a continuous loop resistor element having a first resistor disposed on a central portion of said diaphragm, a second resistor connected to said first resistor and disposed on a peripheral portion of said diaphragm, a third resistor connected to said second resistor and disposed on a central portion of said diaphragm and a fourth resistor connected to said first and third resistors and disposed on a peripheral portion of said diaphragm; and

said first set of electrical terminals comprises a first electrical terminal disposed in ohmic contact with said continuous loop resistor element at the connection between said first and second resistors, a second electrical terminal disposed in ohmic contact with said continuous loop resistor element at the connection between said second and third resistors, a third electrical terminal disposed in ohmic contact with said continuous loop resistor element at the connection of said third and fourth resistor and a fourth electrical terminal disposed in ohmic contact with said continuous loop resistor element at the connection of said first and fourth resistor.

9. A thermally compensated silicon pressure sensor as claimed in claim 7, further comprising:

a sensor package connected to said clamp ring having a first port for applying a first pressure to said top surface of said diaphragm and a second port for applying a second pressure to said bottom surface of said diaphragm.

10. A thermally compensated silicon pressure sensor as claimed in claim 7, further comprising:

a sensor package connected to said clamp ring having a chamber enclosing one of said surfaces of said diaphragm at a fixed pressure and a port for applying a pressure to the other of said surfaces of said diaphragm.

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